

1. An amplifier comprising:
 - a chassis body with a conductive floor configured for supporting amplifier subcircuits;
 - a lid structure for positioning with the chassis body over the subcircuits,
- 5 the lid structure having at least one side wall extending therefrom for surrounding a subcircuit and electrically isolating the subcircuit from other amplifier subcircuits.
2. The amplifier of claim 1 wherein the lid structure has multiple sidewalls for isolating multiple subcircuits.
3. The amplifier of claim 1 wherein the at least one sidewall is integrally formed with the lid structure.
4. The amplifier of claim 1 further comprising a main amplifier subcircuit and an error amplifier subcircuit, the lid structure including a dividing wall extending between the main and error amplifier subcircuits and electrically coupled to the chassis floor for isolating the amplifier subcircuits.

5. The amplifier of claim 1 wherein at least a portion of the main amplifier subcircuit and at least a portion of the error amplifier subcircuit are mounted on a single circuit board, the circuit board having at least one cut-out positioned between the main and error amplifier subcircuits, the dividing wall including an island for passing through the cut-out to electrically couple to the chassis floor.
6. The amplifier of claim 5 wherein the dividing wall includes multiple islands which pass through multiple cut-outs in the circuit board to electrically couple to the chassis floor.
7. The amplifier of claim 1 wherein the lid structure includes at least one other sidewall extending from a side of the lid structure opposite the at least one sidewall for isolating subcircuits on both sides of the lid structure.
8. The amplifier of claim 2 wherein the sidewalls form multiple cavities for isolating the multiple subcircuits.
9. The amplifier of claim 1 wherein the subcircuits are mounted on a circuit board and further comprising a gasket coupled between the sidewall and the circuit board for electrically isolating the subcircuits.

10. An amplifier comprising:

a chassis body;

a lid structure for coupling with the chassis body to contain amplifier subcircuits;

5 at least one of the chassis body and lid structure having at least one side wall extending therefrom for surrounding a subcircuit and electrically isolating the subcircuit from other amplifier subcircuits.

11. The amplifier of claim 10 wherein the at least one chassis body and lid structure has multiple sidewalls for isolating multiple subcircuits.

12. The amplifier of claim 10 wherein the at least one sidewall is integrally formed with one of the chassis body and lid structure.

13. The amplifier of claim 10 further comprising a main amplifier subcircuit and an error amplifier subcircuit, and a dividing wall extending between the main and error amplifier subcircuits and electrically coupled between the lid structure and chassis body for isolating the main and error amplifier subcircuits.

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14. The amplifier of claim 13 wherein at least a portion of the main amplifier subcircuit and at least a portion of the error amplifier subcircuit are mounted on a single circuit board, the circuit board having at least one cut-out positioned between the main and error amplifier subcircuits, the dividing wall including an island for passing through the cut-out to electrically couple
5 between the lid structure and chassis body.

15. The amplifier of claim 14 wherein the dividing wall includes multiple islands which pass through multiple cut-outs in the circuit board to electrically couple between the lid structure and chassis body.

16. The amplifier of claim 10 wherein the at least one chassis body and lid structure includes at least one other sidewall extending from a side thereof opposite the at least one sidewall for isolating subcircuits on both sides of the at least one chassis body and lid structure.

17. The amplifier of claim 10 wherein the subcircuits are mounted on a circuit board and further comprising a gasket coupled between the sidewall and the circuit board for electrically isolating the subcircuits.

18. An amplifier comprising:

a main amplifier subcircuit and an error amplifier subcircuit mounted on a single circuit board;

a chassis body;

5 a lid structure for positioning with the chassis body to contain the circuit board and amplifier subcircuits;

a dividing wall passing through the circuit board between the main amplifier subcircuit and error amplifier subcircuit to electrically isolate the subcircuits.

19. The amplifier of claim 18 wherein the circuit board includes a cut-out formed therein, the dividing wall comprising at least one island passing through the cut-out.

20. The amplifier of claim 18 wherein the dividing wall is electrically coupled between the lid structure and the chassis body.

21. The amplifier of claim 19 wherein the dividing wall includes multiple islands that pass through multiple cut-outs in the circuit board.

22. The amplifier of claim 18 wherein at least one of the main and error amplifier subcircuits includes subcircuits, the lid structure comprising at least one side wall extending therefrom for surrounding a subcircuit and electrically isolating the subcircuit from other amplifier subcircuits.

23. The amplifier of claim 22 wherein the at least one sidewall is integrally formed with the lid structure.

24. The amplifier of claim 22 further comprising additional subcircuits, the lid structure including at least one other sidewall extending from a side of the lid structure opposite the at least one sidewall for isolating subcircuits on both sides of the lid structure.

25. The amplifier of claim 22 further comprising multiple sidewalls that form multiple cavities for isolating multiple subcircuits.

26. The amplifier of claim 22 further comprising a gasket coupled between the sidewall and a circuit board for isolating the subcircuit.

27. A method of isolating subcircuits of an amplifier comprising:
- positioning amplifier subcircuits in a chassis body configured for supporting amplifier subcircuits;
- positioning a lid structure, having at least one side wall extending therefrom, with the chassis body and over the subcircuits for surrounding a subcircuit and electrically isolating the subcircuit from other amplifier subcircuits.
28. The method of claim 27 wherein the at least one sidewall is integrally formed with the lid structure.
29. The method of claim 27 wherein the amplifier subcircuits include a main amplifier subcircuit and an error amplifier subcircuit and further comprising positioning a dividing wall between the main and error amplifier subcircuits and electrically coupling the dividing wall to the chassis body.
30. The method of claim 29 further comprising mounting at least a portion of the main amplifier subcircuit and at least a portion of the error amplifier subcircuit on a single circuit board.
31. The method of claim 30 further comprising passing a portion of the dividing wall through at least one cut-out formed in the single circuit board to electrically couple the dividing wall to the chassis floor.

32. The method of claim 28 wherein the lid structure includes another side wall positioned on a side of the lid structure opposite the at least one side wall extending therefrom, the method further comprising positioning additional amplifier subcircuits in the chassis body proximate the another side wall for isolating subcircuits on both sides of the lid structure.

33. A method of isolating subcircuits of an amplifier comprising:
mounting a main amplifier subcircuit and an error amplifier subcircuit
on a single circuit board in a chassis body;
passing a dividing wall through the circuit board between the main
amplifier subcircuit and error amplifier subcircuit to electrically isolate the
subcircuits.
34. The method of claim 33 further comprising passing a portion of the
dividing wall through a cut-out formed in the circuit board.
35. The method of claim 34 further comprising electrically coupling the
dividing wall to the chassis body.